

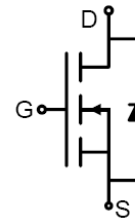


### Features

- N-channel planar MOSFET
- Fast Switching
- Low ON Resistance
- Low Gate Charge

### Application

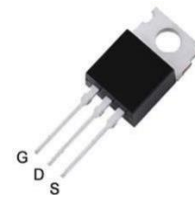
- Switch Mode Power (SMPS)
- Uninterruptible Power Supply (UPS)



Equivalent Circuit

### Key Performance Parameters

| Parameter          | Value | Unit |
|--------------------|-------|------|
| $BV_{DSS}$         | 200   | V    |
| $I_D$              | 18    | A    |
| $R_{DS(ON)_{typ}}$ | 140   | mΩ   |



TO-220

**Table 1. Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$  unless otherwise specified)**

| Symbol         | Parameter  | Value       | Units            |
|----------------|--|-------------|------------------|
| $V_{DSS}$      | Drain-Source Voltage                                 | 200         | V                |
| $V_{GS}$       | Gate-Source Voltage                                  | $\pm 20$    |                  |
| $I_D$          | Continuous Drain Current ( $T_C=25^\circ\text{C}$ )  | 18          | A                |
| $I_{DM}$       | Pulsed Drain Current                                 | 72          |                  |
| $E_{AS}$       | Single Pulse Avalanche Energy                        | 115         | mJ               |
| $P_D$          | Maximum Power Dissipation ( $T_C=25^\circ\text{C}$ ) | 100         | W                |
| $T_J, T_{STG}$ | Operating Junction Storage Temperature Range         | -55 to +150 | $^\circ\text{C}$ |

**Table 2. Thermal Characteristic**

| Symbol     | Parameter                               | Value | Units                     |
|------------|---|-------|---------------------------|
| $R_{thJC}$ | Thermal resistance, Junction to Case    | 1.3   | $^\circ\text{C}/\text{W}$ |
| $R_{thJA}$ | Thermal Resistance, Junction-to-Ambient | 100   | $^\circ\text{C}/\text{W}$ |



**Table 3. Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)**

| Symbol   | Parameter                          | Conditions  | Min  | Typ | Max | Unit |
|--|------------------------------------|---|------|-----|-----|------|
| <b>Static Characteristics</b>                  |                                    |   |      |     |     |      |
| V <sub>DSS</sub>                               | Drain-Source Breakdown Voltage     | V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA                          | 200  | --  | --  | V    |
| V <sub>GS(th)</sub>                            | Gate-Source Threshold Voltage      | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA            | 1    | --  | 2   | V    |
| I <sub>DSS</sub>                               | Zero Gate Voltage Drain Current    | V <sub>DS</sub> = 200V, V <sub>GS</sub> = 0V                          | --   | --  | 1   | μA   |
| I <sub>GSSF</sub>                              | Gate-Body Leakage Current, Forward | V <sub>DS</sub> = 0V, V <sub>GS</sub> = 20V                           | --   | --  | 100 | nA   |
| I <sub>GSSR</sub>                              | Gate-Body Leakage Current, Reverse | V <sub>DS</sub> = 0V, V <sub>GS</sub> = -20V                          | -100 | --  | --  |      |
| R <sub>DS(ON)</sub>                            | Drain-Source On-State Resistance   | V <sub>GS</sub> = 10V, I <sub>D</sub> = 9A                            | --   | 140 | 180 | mΩ   |
| <b>Dynamic Characteristics</b>                 |                                    |   |      |     |     |      |
| C <sub>iss</sub>                               | Input Capacitance                  | V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V, f = 1.0MHz               | --   | 863 | --  | pF   |
| C <sub>oss</sub>                               | Output Capacitance                 |   | --   | 165 | --  |      |
| C <sub>rss</sub>                               | Reverse Transfer Capacitance       |   | --   | 90  | --  |      |
| t <sub>d(on)</sub>                             | Turn-on Delay Time                 | V <sub>DD</sub> = 100V, I <sub>D</sub> = 18A<br>R <sub>g</sub> = 25Ω  | --   | 38  | --  | ns   |
| t <sub>r</sub>                                 | Turn-on Rise Time                  |   | --   | 45  | --  |      |
| t <sub>d(off)</sub>                            | Turn-off Delay Time                |   | --   | 255 | --  |      |
| t <sub>f</sub>                                 | Turn-off Fall Time                 |   | --   | 72  | --  |      |
| Q <sub>g</sub>                                 | Total Gate Charge                  | I <sub>D</sub> = 18A, V <sub>DD</sub> = 160V<br>V <sub>GS</sub> = 10V | --   | 53  | --  | nC   |
| Q <sub>gs</sub>                                | Gate-Source Charge                 |   | --   | 5.8 | --  |      |
| Q <sub>gd</sub>                                | Gate-Drain Charge                  |   | --   | 30  | --  |      |
| <b>Source-Drain Body Diode Characteristics</b> |                                    |   |      |     |     |      |
| V <sub>SD</sub>                                | Body Diode Forward Voltage         | V <sub>GS</sub> = 0V, I <sub>SD</sub> = 18A                           | --   | --  | 1.5 | V    |
| I <sub>S</sub>                                 | Continuous Diode Forward Current   | T <sub>C</sub> = 25°C   | --   | --  | 18  | A    |
| t <sub>rr</sub>                                | Reverse Recovery Time              | I <sub>S</sub> = 18A  | --   | 180 | --  | ns   |
| Q <sub>rr</sub>                                | Reverse Recovery Charge            | di/dt = 100A/μs   | --   | 0.9 | --  | μC   |



Figure 1. Output Characteristics ( $T_J = 25^\circ\text{C}$ )

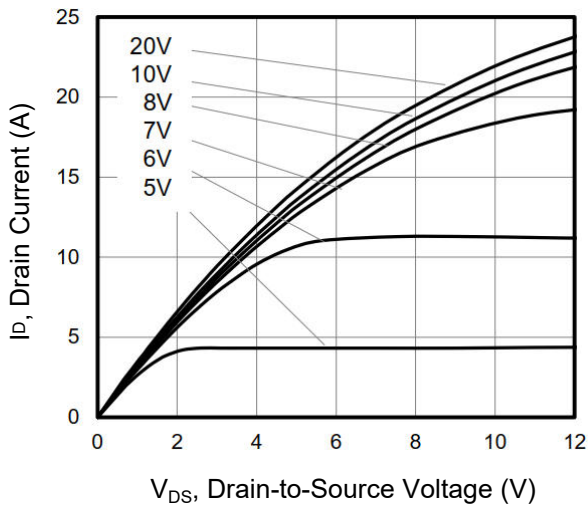


Figure 2. Body Diode Forward Voltage

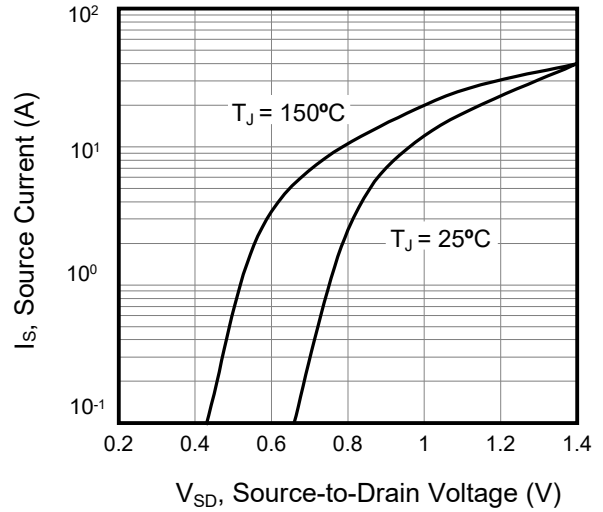


Figure 3. Drain Current vs. Temperature

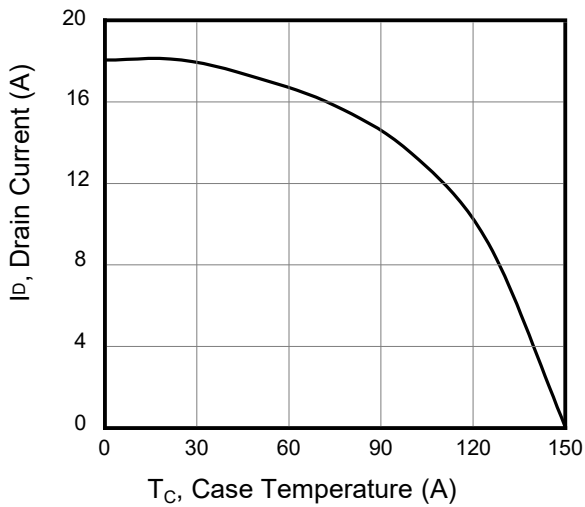


Figure 4.  $BV_{DSS}$  Variation vs. Temperature

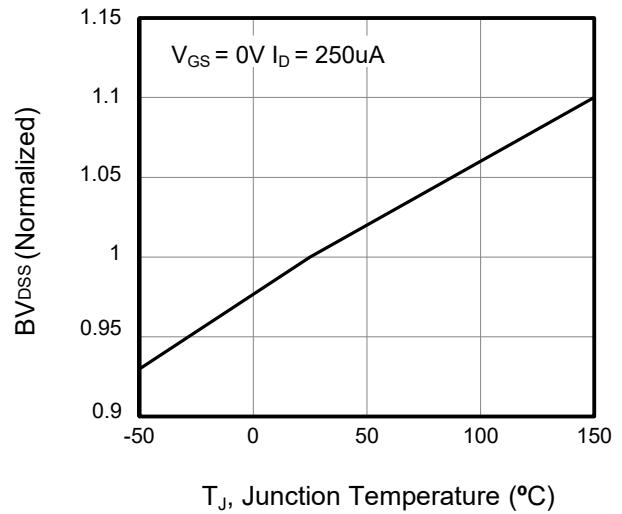


Figure 5. Transfer Characteristics

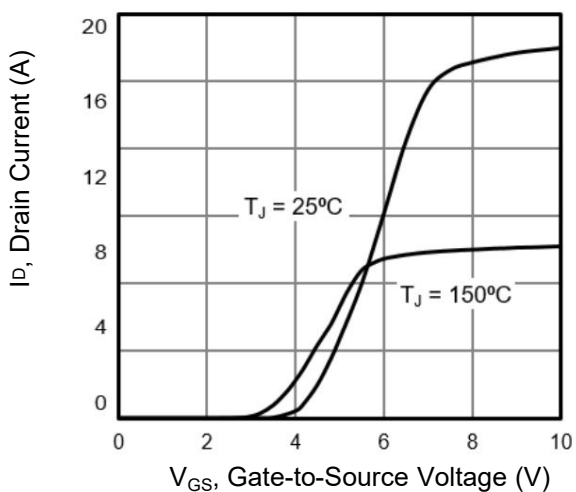


Figure 6. On-Resistance vs. Temperature

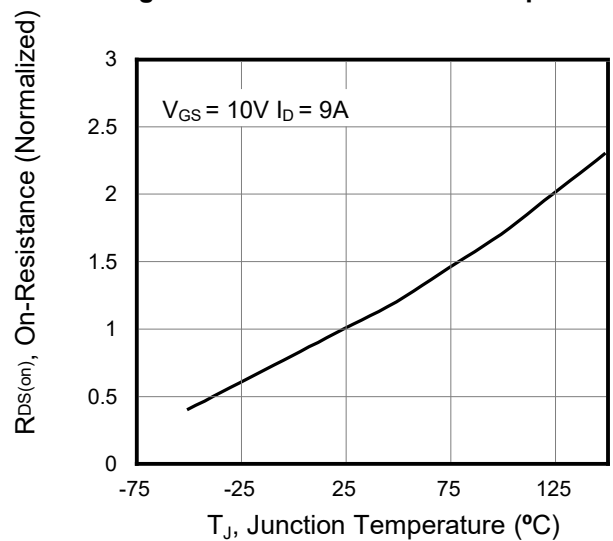




Figure 7. Capacitance

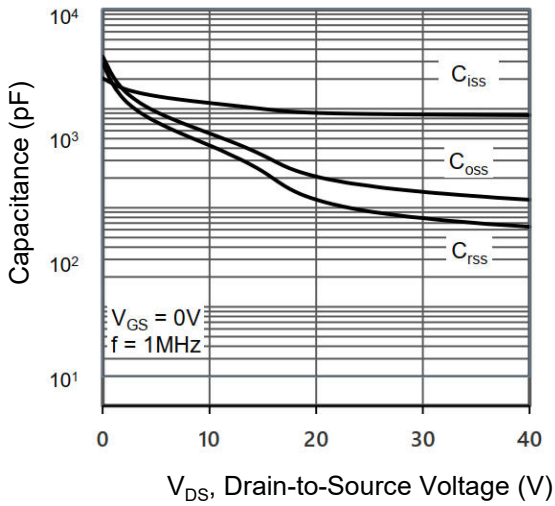


Figure 8. Gate Charge

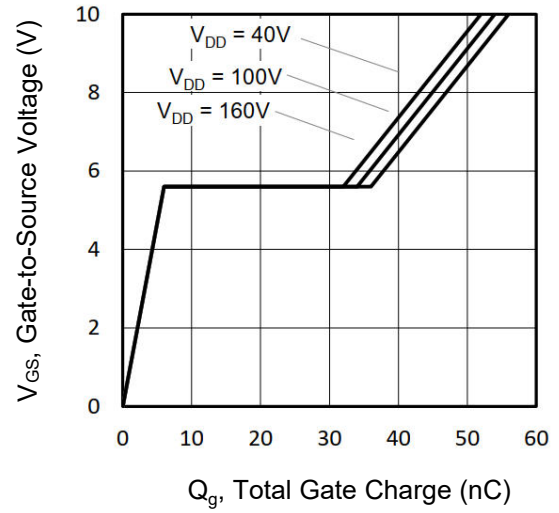


Figure 9. Transient Thermal Impedance

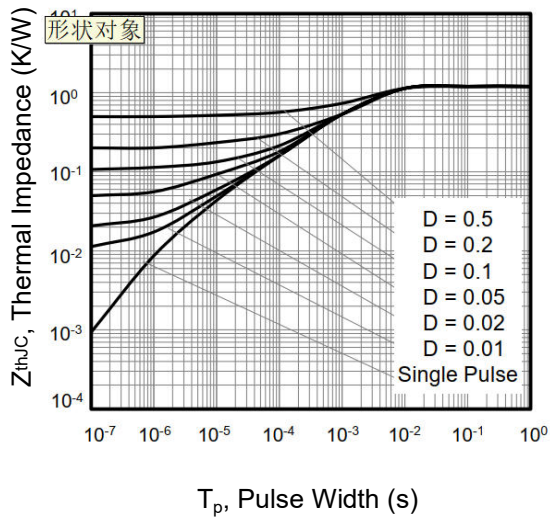




Figure A: Gate Charge Test Circuit and Waveform

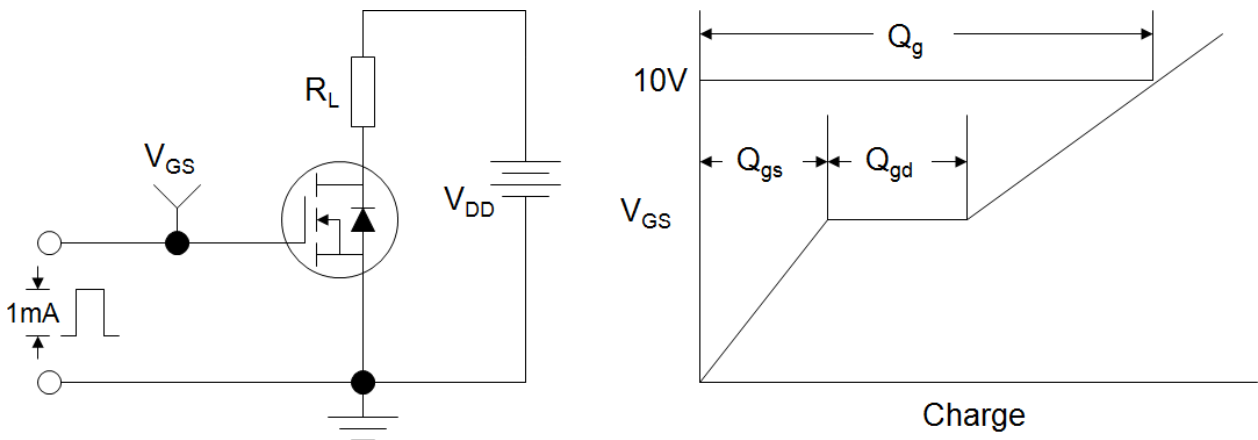


Figure B: Resistive Switching Test Circuit and Waveform

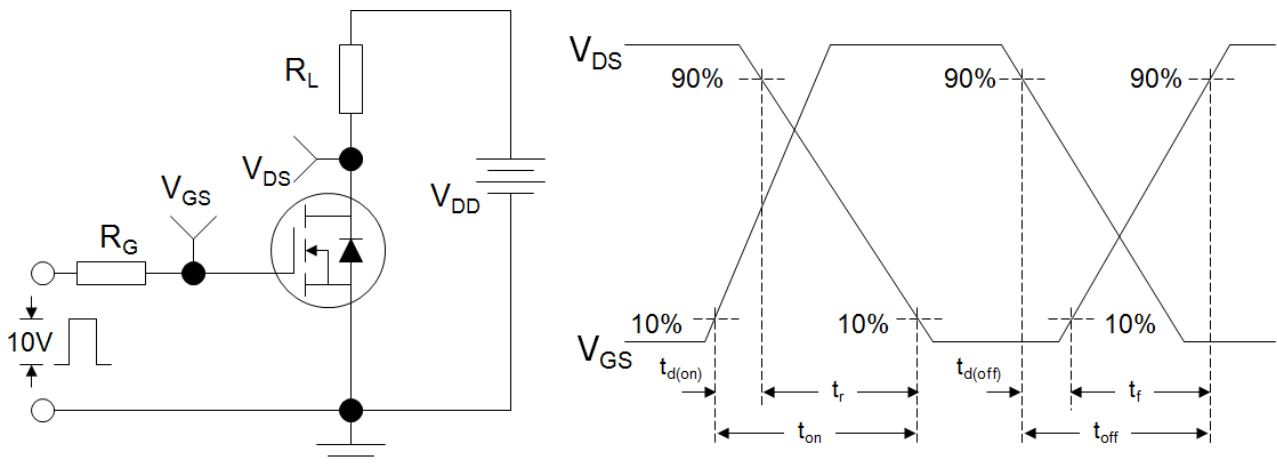
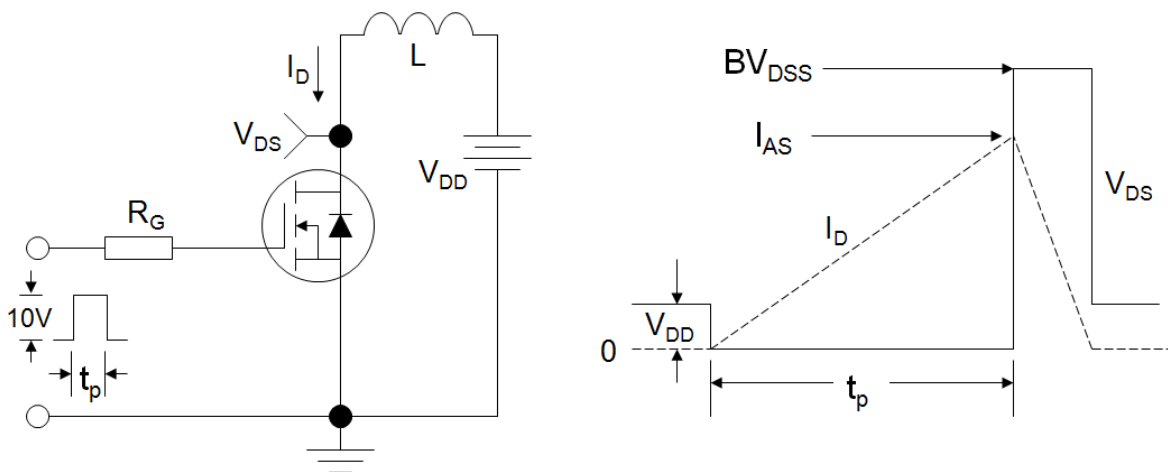


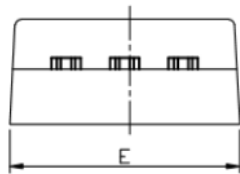
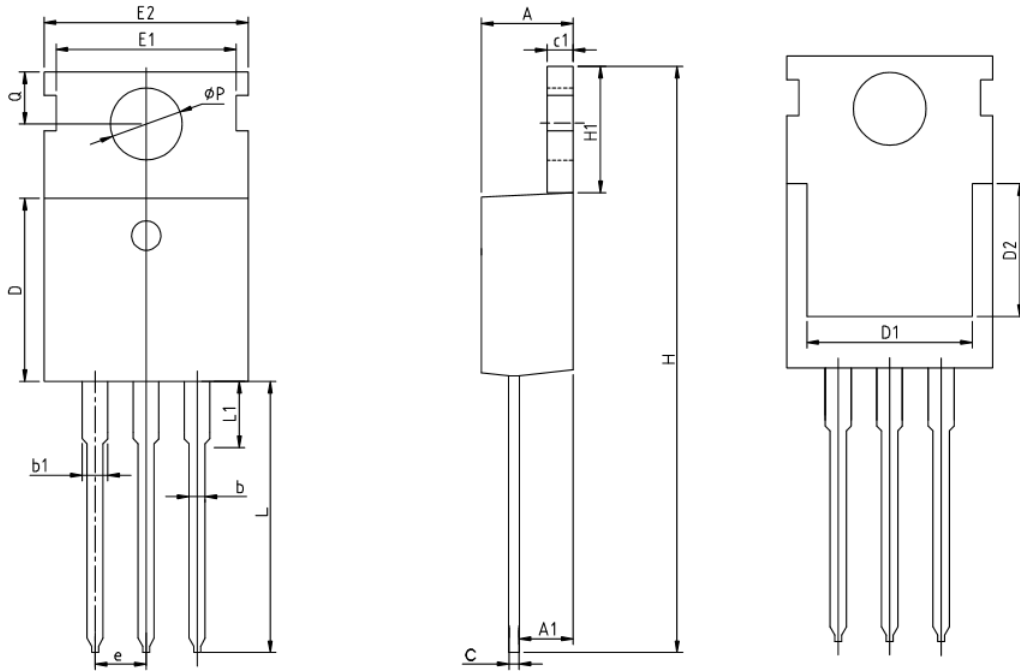
Figure C: Unclamped Inductive Switching Test Circuit and Waveform



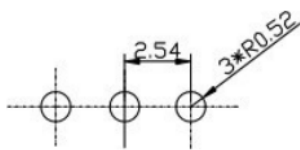


Package Dimensions

TO-220



RECOMMENDED LAND PATTERN



UNIT:mm

|    | MIN   | NOM     | MAX   |
|----|-------|---------|-------|
| A  | 4.40  | 4.60    | 4.80  |
| A1 | 2.25  | 2.40    | 2.55  |
| b  | 0.72  | 0.82    | 0.92  |
| b1 | 1.12  | 1.27    | 1.42  |
| c  | 0.40  | 0.50    | 0.60  |
| c1 | 1.20  | 1.30    | 1.40  |
| D  | 8.80  | 9.10    | 9.40  |
| D1 | 7.75  | 7.95    | 8.15  |
| D2 | 6.55  | 6.75    | 6.95  |
| e  |       | 2.54BSC |       |
| E  | 9.65  | 10.00   | 10.35 |
| E1 |       | 8.70    |       |
| E2 | 9.70  | 10.00   | 10.30 |
| H  | 28.70 | 29.20   | 29.70 |
| H1 | 6.25  | 6.50    | 6.85  |
| L  | 13.20 | 13.50   | 13.80 |
| L1 | 2.80  | 3.10    | 3.40  |
| Q  | 2.60  | 2.80    | 3.00  |
| ΦP | 3.45  | 3.60    | 3.75  |



## **Disclaimer**

Brunei has made reasonable commercial efforts to ensure that the information given in this datasheet is correct. However, it must clearly be understood that such information is for guidance only and does not constitute any representation or form part of any offer or contract.

For documents and material available from this datasheet, Brunei does not warrant or assume any legal liability or responsibility for the accuracy, completeness, or usefulness of any information, product, technology or process disclosed hereunder.

Brunei reserves the rights to at its own discretion to make any changes or improvements to this datasheet. Unless said datasheet is incorporated into the formal contract, any customer should not rely on the information as any specification or product parameters duly committed by Brunei Customers are hereby advised to verify that the information contained herein is current and complete before the entering of any contract or acknowledgement of any purchase order. Accordingly, all products specified hereunder shall be sold subject to Brunei's terms and conditions supplied at the time of order acknowledgement. Except where agreed upon by contractual agreement, testing of all parameters of each product is not necessarily performed.

Brunei does not warrant or convey any license either expressed or implied under its patent rights, nor the rights of others. Reproduction of information contained herein shall be only permissible if such reproduction is without any modification or alteration. Reproduction of this information with any alteration is an unfair and deceptive business practice. Brunei is not responsible or liable for such altered documentation.

Resale of Brunei's products with statements different from or beyond the parameters stated by Brunei for that product or service voids all express or implied warranties for the associated Brunei's product or service and is unfair and deceptive business practice. Brunei is not responsible or liable for any such statements.

Brunei's products are not authorized for use as critical components in life support devices or systems without the express written approval of Brunei. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.